

SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31B475KOELNNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 4.7 µF, 16V, ±10%, X7R, 1206

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>B</u> <u>475</u> <u>K</u> <u>O</u> <u>E</u> <u>L</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor		
2	Size	1206 (inch code)	L: 3.2 ± 0.2 mm W:	1.6 ± 0.2 mm
			Thickness division	Low profile
3	Dielectric	X7R	Inner electrode	Ni
4	Capacitance	4.7 μF	Termination	Cu
(5)	Capacitance	±10 %	Plating	Sn 100% (Pb Free)
	tolerance		Product	Normal
6	Rated Voltage	16 V	Special	Reserved for future use
7	Thickness	1.1 ± 0.1 mm	① Packaging	Embossed Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition	
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms	
Tan δ (DF)	0.1 max.		
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.	
Resistance	Whichever is Smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	250% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	X7R		
Characterisitcs (From -55 ℃ to 125 ℃, Capacitance change shoud be within ±15%)		ge shoud be within ±15%)	
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)	
		with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder	
	is to be soldered newly	235±5℃, 5±0.5sec.	
		2) SnAg3.0Cu0.5 solder	
		245±5℃, 3±0.3sec.	
		(preheating : 80~120℃ for 10~30sec.)	
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.	
Soldering heat	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Humidity	Capacitance change : within ±12.5%	40±2°C, 90~95%RH, 500+12/-0hrs
	Tan δ : 0.125 max	
	IR : 25MΩ·μF or Over	
Moisture	Capacitance change : within ±12.5%	With rated voltage
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR: 12.5MΩ·μF or Over	
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage
Resistance	Tan δ : 0.125 max	Max. operating temperature
	IR : 25MΩ·μF or Over	
		1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25 °C
		→ Max. operating temperature → 25°C
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.